

Figure 1. Block Diagram

Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description
1	CLKIN	I	External reference Clock input.
2	PD# / OE	I	Power Down. Pull LOW to enable Power Down. Outputs will be tri-stated when power down is enabled. Pull HIGH to disable power down and enable output. NO default state.
3	FS	I	Frequency Select .NO default state. Refer to the Frequency Selection table
4	GND	Р	Ground
5	ModOUT	0	Buffered modulated Timing-Safe clock output
6	MR	I	Modulation Rate Select. When LOW, selects Low Modulation Rate. Selects High Modulation Rate when pulled HIGH. Has an internal pull-up resistor.
7	SSEXTR	I	Analog Deviation Selection through external resistor to GND.
8	V _{DD}	Р	Supply Voltage

Table 2. FREQUENCY SELECTION TABLE

FS	Frequency (MHz)
0	18–36
1	36–72

Table 3. OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{DD}	Supply Voltage		3.6	V
T _A	Operating Temperature		+85	°C
CL	Load Capacitance		15	pF
C _{IN}	Input Capacitance		7	pF

Table 4. ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Rating	Unit
$V_{DD,} V_{IN}$	Voltage on any input pin with respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage temperature	-65 to +125	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C
TJ	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22-A114-B)	2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min	Тур	Max	Unit
V _{DD}	Supply Voltage			2.3	2.7	3.6	V
V _{IH}	Input HIGH Voltage			0.65 * V _{DD}			V
V _{IL}	Input LOW Voltage					0.35 * V _{DD}	V
I _{IH}	Input HIGH Current	V _{IN} = V _{DD}	V _{IN} = V _{DD}			10	μA
Ι _{ΙL}	Input LOW Current	V _{IN} = 0 V for MR pir	1			10	μA
V _{OH}	Output HIGH Voltage	I _{OH} = -16 mA		0.75 * V _{DD}			V
V _{OL}	Output LOW Voltage	I _{OL} = 16 mA				0.25 * V _{DD}	V
I _{CC}	Static Supply Current	PD#/OE pin pulled to GND				10	μA
I _{DD}	Dynamic Supply Current	Unloaded Output	FS = 0, @ 18 MHz		6	10	mA
			FS = 0, @ 24 MHz		7	12	
			FS = 0, @ 36 MHz		10	17	
			FS = 1, @ 36 MHz		9	14	
			FS = 1, @ 48 MHz		11	19	
			FS = 1, @ 72 MHz		16	28	
Zo	Output Impedance		•		13		Ω

Table 6. AC ELECTRICAL CHARACTERISTICS

Parameter	Test Conditions	Min	Тур	Max	Unit	
Input Frequency	FS = 0	18	24	36	MHz	
	FS = 1	36	48	72		
ModOUT	FS = 0	18	24	36		
	FS = 1	36	48	72		
Duty Cycle (Note 1 and 2)	Measured at V _{DD} / 2	45	50	55	%	
Rise Time (Note 1 and 2)	Measured between 20% to 80%		0.8	1.2	ns	
Fall Time (Note 1 and 2)	Measured between 80% to 20%		0.8	1.2	ns	

1. All parameters are specified with 15 pF loaded output.

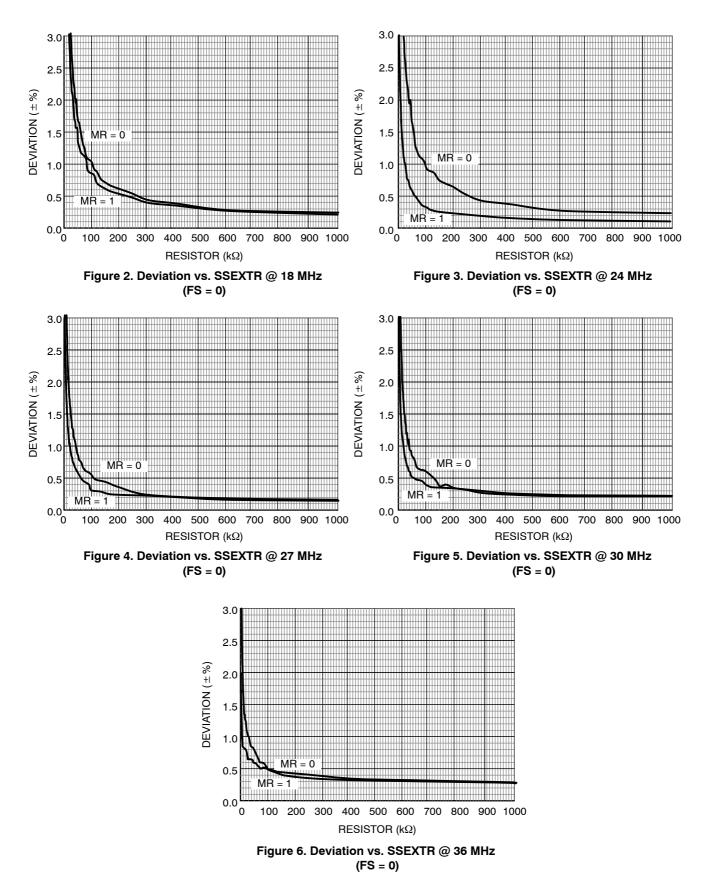
2. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Table 6. AC ELECTRICAL CHARACTERISTICS

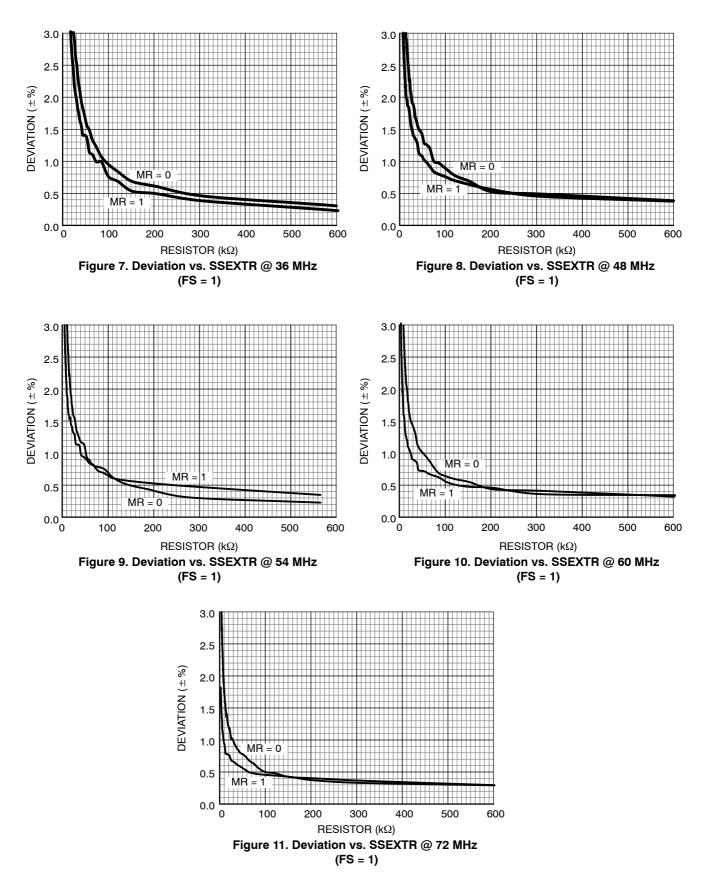
Parameter	Test C	Test Conditions		Тур	Max	Unit
Cycle-to-Cycle Jitter (Note 2)	with SSEXTR pin OPEN	FS = 0, 18 MHz		±250	±350	ps
		FS = 0, 24 MHz		±150	±225	
		FS = 0, 36 MHz		±75	±125	
		FS = 1, 36 MHz		±150	±200	
		FS = 1, 48 MHz		±100	±150	
		FS = 1, 72 MHz		±75	±125	
PLL Lock Time (Note 2)		Stable power supply, valid clock presen- ted on CLKIN pin, PD# toggled from Low to High			1	ms

All parameters are specified with 15 pF loaded output.
Parameter is guaranteed by design and characterization. Not 100% tested in production.

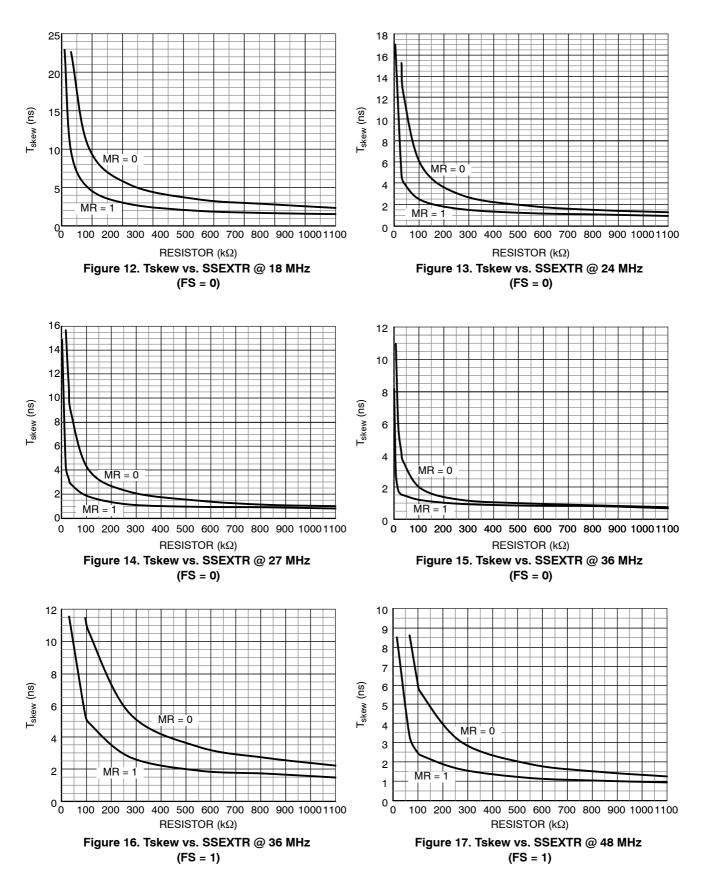
DEVIATION VERSUS SSEXTR RESISTANCE CHARTS



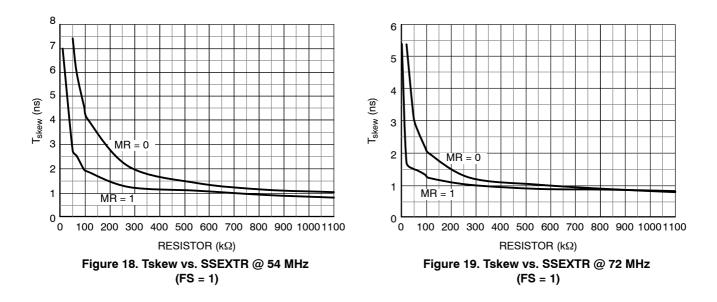




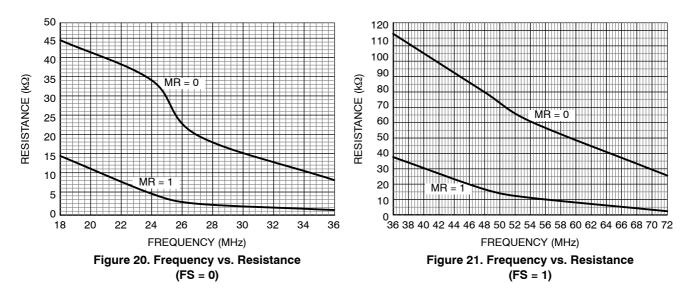
TSKEW VERSUS SSEXTR RESISTANCE CHARTS



TSKEW VERSUS SSEXTR RESISTANCE CHARTS

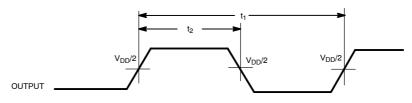






NOTE: Device-to-Device variation of Deviation and Tskew is $\pm 10\%$

SWITCHING WAVEFORMS





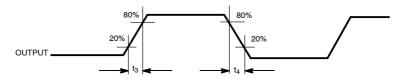
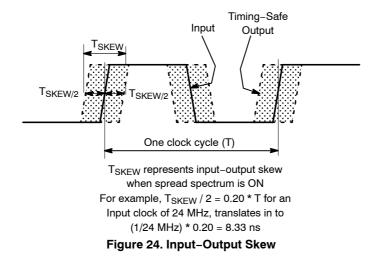
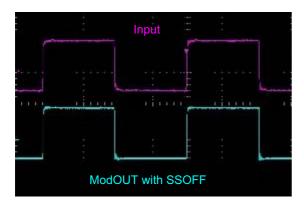


Figure 23. Output Rise/Fall Time





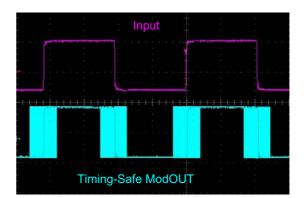
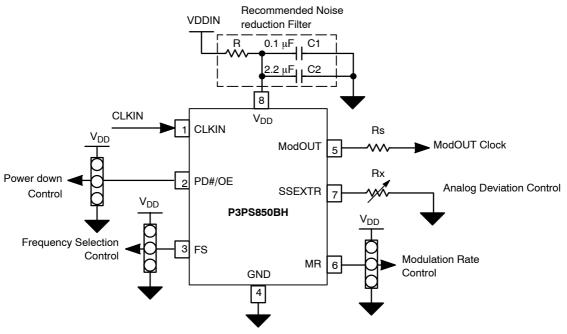


Figure 25. Typical Example of Timing–Safe Waveform



NOTE: Refer Pin Description table for Functionality details.

Figure 26. Typical Application Schematic

PCB Layout Recommendation

For optimum device performance, following guidelines are recommended.

- Dedicated V_{DD} and GND planes.
- The device must be isolated from system power supply noise. A 0.1 μ F and a 2.2 μ F decoupling capacitor should be mounted on the component side of the board as close to the V_{DD} pin as possible. No vias should be used between the decoupling capacitor and V_{DD} pin. The PCB trace to V_{DD} pin and the ground via should be kept as short as possible. All the V_{DD} pins should have decoupling capacitors.
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.
- A typical layout is shown in Figure 27.

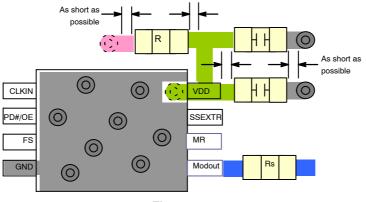


Figure 27.

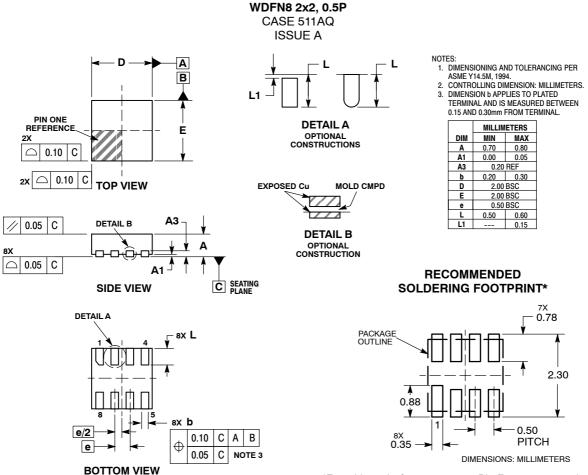
ORDERING INFORMATION

Part Number	Top Marking	Temperature	Package Type	Shipping [†]
P3PS850BHG-08CR	DG	–20°C to +85°C	8–Pin (2 mm x 2 mm) WDFN(TDFN) (Pb–Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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